

**RECEIVED
CENTRAL FAX CENTER****OCT 12 2006****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of:

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LIN ET AL.

Serial No.: 10/055,560

Filed: January 22, 2002

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For: INTEGRATED CHIP PACKAGE

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SUBSTRATE AND METHOD OF

MANUFACTURING THE SAME

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Examiner: MITCHELL, JAMES M

Art Unit: 2813

Docket No.: MEGP0009USA

RESPONSE TO OFFICE ACTION

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Mail Stop AF

Commissioner for Patents

P. O. Box 1450

Alexandria, VA 22313-1450

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Dear Sir:

The Office Action mailed Jul. 13, 2006 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

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